



FULLY AUTOMATIC SINGLE SPINDLE DICING SAWS

7224

4" Spindle

Hard material dicing such as glass and ceramic



Features & Benefits

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results



Workpiece Size	Ø 8"	
Spindle	30K rpm / 2.5 kW	
Blade Size	4" - 5"	
Y Axis	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis	Air Slide	
Z Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
θ Axis	Repeatability	4 arc-sec
	Stroke	380°
Cleaning Station	Full rinse and dry cycle	
	Spinning speed	100-2,000 rpm
	Cleaning Method	Atomized cleaning capabilities
Utilities	Electrical	
	200-240 VAC, 50/60 Hz, single phase	
Dimensions	(W x D x H) mm	965 x 1460 x 1700
	Weight	1,200kg

Materials:

Glass on Silicon | MEMS | Package Singulation (BGA & QFN) | LTCC | PCB | Hard Materials

7304

4" Spindle

Hard material dicing such as glass and ceramic



Features & Benefits

- Support 4"-5" blade O.D.
- Internal air flow management minimizing product contamination
- Multi panel dicing
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Custom process solution
- UV LED curing system
- Exhaust impeller
- Height Measuring Tool (HMT)
- Bar code reader (Internal or external)
- SECS GEM communication protocol



Workpiece Size	9" X 12"	
Spindle	30K rpm / 2.5 kW	
Blade Size	4" - 5"	
Y Axis	Control	Linear encoder
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis	Air Slide	
Z Axis	Resolution	0.2 µm
	Repeatability	1.0 µm
θ Axis	Repeatability	4 arc-sec
	Stroke	380°
Cleaning Station	Full rinse and dry cycle	
	Spinning speed	100-2,000 rpm
	CleaningMethod	Atomized cleaning capabilities
Utilities	Electrical	
	200-240 VAC, 50/60 Hz, single phase	
Dimensions	(W x D x H) mm	1100 x 1785 x 1700
	Weight	1,350kg

Materials:

Glass | Ceramc | PZT | PCB | Alumina | More